



08-06-01

Receipt
#9

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Byung Hoon Ahn, Jae Hun Ku, Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do

Assignee: Amkor Technology, Inc.

Title: Lead Frame And Semiconductor Package Made Using The Leadframe

Serial No.: 09/845,601 Filing Date: April 26, 2001

Examiner: Not Yet Assigned Group Art Unit: 2811

Docket No.: AB-1134 US

San Jose, California
August 2, 2001

COMMISSIONER FOR PATENTS
Office of Initial Patent Examination
Customer Service Center
Washington, D.C. 20231

REQUEST FOR CORRECTED FILING RECEIPT

Dear Sir:

Applicants hereby request the correction of the filing date listed on the Official Filing Receipt for the above-identified patent application:

This Request is submitted because the actual filing date is April 26, 2001, not April 27, 2001. The application was deposited in the U.S. Express Mail on April 26, 2001, as indicated by the following evidence:

1. Express Mail Receipt EL 710 212 794 US marked with the date April 26, 2001;
2. Application Transmittal letter dated April 26, 2001 and bearing Express Mail No. EL 710 212 794 US.

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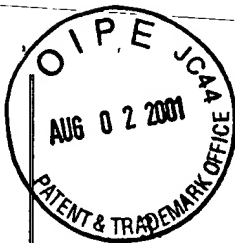
OCT 23 2001

OFFICE OF PETITIONS

Serial No. 09/845,601

LAW OFFICES OF
SKJERNEN MORRILL
MacPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979



First page of the above-named patent application, which bears Express Mail
No. EL 701 202 794 US;

4. Return receipt postcard for the above-named patent application which includes
a bar code label with a filing date which was erroneously dated April 27, 2001.

Accordingly, Applicants submit that the filing date of the application should be April
26, 2001.

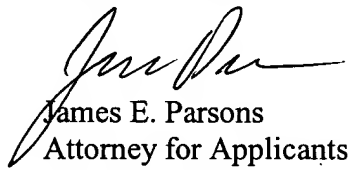
Because this was not an error on the part of Applicants, Applicants believe no fee is
required.

Attached is a copy of the Filing Receipt having the above errors and the changes noted
thereon. Therefore, it is respectfully requested that a corrected Filing Receipt be issued.

If this action does not lead to issuance of a corrected Official Filing Receipt as
requested, please contact the undersigned at (408) 453-9200.

EXPRESS MAIL LABEL NO:
EL 701 020 439 US

Respectfully submitted,


James E. Parsons
Attorney for Applicants
Reg. No. 34,691

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SKJERVEN MORRILL
MacPHERSON LLP

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(408) 453-9200
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SKJERVEN
MORRILL
MACPHERSON LLP

Docket No.: AB-1134 US

April 26, 2001

Box Patent Application
Commissioner For Patents
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventors: Byung Hoon Ahn, Jae Hun Ku, Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do

Title: Leadframe And Semiconductor Package Made Using The Leadframe

X Return Receipt Postcard;
X This Transmittal Letter (in duplicate);
21 pages Specification (not including claims);
4 pages Claims;
1 page Abstract;
7 Sheets of Drawings (Figs. 1a, 1b, 1c, 2a, 2b, 3a, 3b, 3c, 4a, 4b, 5a, 5b, 6a, 6b);
3 pages Declaration For Patent Application and Power of Attorney (signed by Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do);
1 page Recordation Form Cover Sheet (in duplicate); and
3 pages Assignment (signed by Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do).

CLAIMS AS FILED

For	Number <u>Filed</u>		Number <u>Extra</u>		Rate		Basic Fee
Total Claims	20	-20	=	0	x	\$ 18.00	= \$ 710.00
							\$ 0.00

Independent Claims	4	-3	=	1	x	\$80	=	\$ 80.00
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☐ Fee of _____ for the first filing of one or more multiple dependent claims per application

☐ Fee for Request for Extension of Time

Please make the following charges to Deposit Account 19-2386:

☒ Total fee for filing the patent application in the amount of \$ 790.00
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

EXPRESS MAIL LABEL NO:

EL 710 212 794 US

Respectfully submitted,

James E. Parsons
Attorney for Applicants
Reg. No. 34,691

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AB-1134 US - 748535 v2

EXPRESS MAIL LABEL NO:
EL 710 212 794 US

**LEADFRAME AND SEMICONDUCTOR PACKAGE MADE
USING THE LEADFRAME**

Byung Hoon Ahn

Jae Hun Ku

Young Suk Chung

Suk Gu Ko

Sung Sik Jang

Young Nam Choi

Won Chul Do

BACKGROUND OF THE INVENTION

A typical package for a semiconductor chip includes an internal leadframe, which functions as a substrate for the package. The leadframe includes a central metal chip pad and a plurality of leads. A body of a hardened, insulative encapsulant material covers the chip, chip pad, and an inner portion of each of the leads. The encapsulant material is provided both above and below the chip pad and leads.

The semiconductor chip is mounted on the chip pad and is electrically connected to the leads. In particular, the chip includes a plurality of bond pads, each of which is electrically connected by a conductor (e.g., a wire) to an encapsulated inner portion of one of the leads. An outer portion of each lead extends outward from the body of encapsulant material, and serves as an input/output terminal for the package. The outer portion of the leads may be bent into various configurations, such as a J lead configuration or a gull wing configuration.

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**BOX PATENT APPLICATION
COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231**

Inventors: Byung Hoon Ahn, Jae Hun Ku, Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do
Title: Leadframe And Semiconductor Package Made Using The Leadframe
Attorney Docket: AB-1134 US

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BY DOCKET DEPT.**

ENCLOSED:

- X This Return Receipt Postcard;
- X Transmittal Letter (in duplicate);
- 21 pages Specification (not including Claims);
- 4 pages Claims;
- 1 page Abstract;
- 7 sheets of Drawings (Figs. 1a, 1b, 1c, 2a, 3b, 3a, 3b, 3c, 4a, 4b, 5a, 5b, 6a, 6b);
- 3 pages Declaration For Patent Application and Power of Attorney (signed by Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do);
- 1 Page Recordation Form Cover Sheet (in duplicate); and
- 3 pages Assignment (signed by Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do).

MAY 09 2001

SKJERVEN, MORRILL, MACPHERSON,
LLP.

JEP/cb

April 26, 2001

VIA EXPRESS MAIL NO.: EL 710 212 794 US

750860 v1



**BOX PATENT APPLICATION
COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231**

Inventors: Byung Hoon Ahn, Jae Hun Ku, Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do
Title: Leadframe And Semiconductor Package Made Using The Leadframe
Attorney Docket: AB-1134 US

ENCLOSED:

- X This Return Receipt Postcard;
- X Transmittal Letter (in duplicate);
- 21 pages Specification (not including Claims);
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- 1 page Abstract;
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JEP/cb

April 26, 2001

VIA EXPRESS MAIL NO.: EL 710 212 794 US

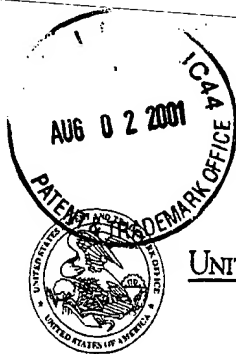
750860 v1

EL 710212794US

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UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/845,601	04/27/2001	2811	790	AB-1134 US	7	20	4

CONFIRMATION NO. 2578

FILING RECEIPT



OC00000006232791

James E. Parsons
SKJERVEN MORRILL MacPHERSON LLP
Suite 700
25 Metro Drive
San Jose, CA 95110-1349

Date Mailed: 06/27/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. **If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).**

Applicant(s)

Byung Hoon Ahn, Seoul, KOREA, REPUBLIC OF;
Jae Hun Ku, Seoul, KOREA, REPUBLIC OF;
Young Suk Chung, Seoul, KOREA, REPUBLIC OF;
Suk Gu Ko, Goyang-shi, KOREA, REPUBLIC OF;
Sung Sik Jang, Hanam-shi, KOREA, REPUBLIC OF;
Young Nam Choi, Seoul, KOREA, REPUBLIC OF;
Won Chul Do, Seoul, KOREA, REPUBLIC OF;

Domestic Priority data as claimed by applicant

Foreign Applications

REPUBLIC OF KOREA 2000-22590 04/27/2000
REPUBLIC OF KOREA 2000-41644 07/20/2000
REPUBLIC OF KOREA 2000-63021 10/25/2000

If Required, Foreign Filing License Granted 06/27/2001

Projected Publication Date: To Be Determined - pending completion of Missing Parts

Non-Publication Request: No

Early Publication Request: No

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Title

Leadframe and semiconductor package made using the leadframe

Preliminary Class

257

Data entry by : VORACHACK, CHUNTASORN Team : OIPE

Date: 06/27/2001



**LICENSE FOR FOREIGN FILING UNDER
Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15**

GRANTED

The applicant has been granted a license under 35 U.S.C. 184, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" followed by a date appears on this form. Such licenses are issued in all applications where the conditions for issuance of a license have been met, regardless of whether or not a license may be required as set forth in 37 CFR 5.15. The scope and limitations of this license are set forth in 37 CFR 5.15(a) unless an earlier license has been issued under 37 CFR 5.15(b). The license is subject to revocation upon written notification. The date indicated is the effective date of the license, unless an earlier license of similar scope has been granted under 37 CFR 5.13 or 5.14.

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The grant of a license does not in any way lessen the responsibility of a licensee for the security of the subject matter as imposed by any Government contract or the provisions of existing laws relating to espionage and the national security or the export of technical data. Licensees should apprise themselves of current regulations especially with respect to certain countries, of other agencies, particularly the Office of Defense Trade Controls, Department of State (with respect to Arms, Munitions and Implements of War (22 CFR 121-128)); the Office of Export Administration, Department of Commerce (15 CFR 370.10 (j)); the Office of Foreign Assets Control, Department of Treasury (31 CFR Parts 500+) and the Department of Energy.

NOT GRANTED

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PLEASE NOTE the following information about the Filing Receipt:

- The articles such as "a," "an" and "the" are not included as the first words in the title of an application. They are considered to be unnecessary to the understanding of the title.
- The words "new," "improved," "improvements in" or "relating to" are not included as first words in the title of an application because a patent application, by nature, is a new idea or improvement.
- The title may be truncated if it consists of more than 500 characters (letters and spaces combined).
- The docket number allows a maximum of 25 characters.
- If your application was submitted under 37 CFR 1.10, your filing date should be the "date in" found on the Express Mail label. If there is a discrepancy, you should submit a request for a corrected Filing Receipt along with a copy of the Express Mail label showing the "date in."
- The title is recorded in sentence case.

Any corrections that may need to be done to your Filing Receipt should be directed to:

Assistant Commissioner for Patents
Office of Initial Patent Examination
Customer Service Center
Washington, DC 20231

